

Amendments to the Specification

Please amend the Abstract as follows

Consistent with an example embodiment, an electronic device comprises a semiconductor device, particularly an integrated circuit, and a carrier substrate with conductive layers on the first side and the second side, and voltage supply and ground connections mutually arranged according to a chessboard pattern. These connections extend in a direct path through vertical interconnects and bumps to bond pads at the integrated circuit, which bond pads are arranged in a corresponding chessboard pattern. As a result, an array of direct paths is provided, wherein the voltage supply connections form as much as possible the coaxial center conductors of a coaxial structure.

~~The electronic device comprises a semiconductor device (10), particularly an integrated circuit, and a carrier substrate (20) with conductive layers on the first side (21) and the second side (22), and voltage supply (62) and ground connections (61) mutually arranged according to a chessboard pattern. These connections (61,62) extend in a direct path through vertical interconnects and bumps (41,42) to bond pads at the integrated circuit, which bond pads are arranged in a corresponding chessboard pattern. As a result, an array of direct paths is provided, wherein the voltage supply connections (62) form as much as possible the coaxial center conductors of a coaxial structure.~~

~~Fig. 4~~